

200V P-Channel Enhancement Mode MOSFET

Description

The 9P20D is silicon P-channel Enhanced VDMOSFETs, is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency.

General Features

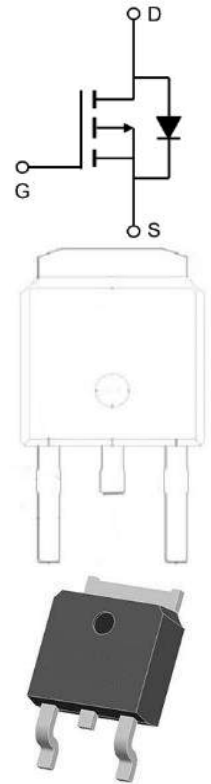
$V_{DS} = -200V, I_D = -9A$

$R_{DS(ON)} < 0.75\Omega @ V_{GS} = 10V$

Application

Power amplifier

motor drive



Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	- 200	V
VGS	Gate-Source Voltage	± 20	V
ID	Continuous Drain Current $T_C = 25^\circ C$	-8.7	A
	Continuous Drain Current $T_C = 100^\circ C$	-3.6	A
IDM	Pulsed Drain Current ^a	- 22.8	A
EAS	Single Pulse Avalanche Energy ^b	570	mJ
IAR	Repetitive Avalanche Current ^a	-8.7	A
EAR	Repetitive Avalanche Energy ^a	5.5	mJ
Pd	Maximum Power Dissipation $T_C = 25^\circ C$	55	W
	Maximum Power Dissipation (PCB Mount) ^e $T_A = 25^\circ C$	2.5	W
dV/dt	Peak Diode Recovery dV/dt ^c	- 5.5	V/ns
TJ, Tstg	Operating Junction and Storage Temperature Range	- 55 to + 150	$^\circ C$
RthJA	Maximum Junction-to-Ambient	110	$^\circ C/W$
RthJA	Maximum Junction-to-Ambient (PCB Mount) ^a	50	$^\circ C/W$
RthJC	Maximum Junction-to-Case (Drain)	2.2	$^\circ C/W$

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Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{DS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$	-200	-	-	V
$\Delta V_{DS}/T_J$	V_{DS} Temperature Coefficient	Reference to 25°C , $I_D = -250\ \mu\text{A}$	-	-0.1	-	V/ $^\circ\text{C}$
V _{GS(th)}	Gate-Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-2.0	-3.5	-4.0	V
R _{DS(on)}	Drain-Source On-State Resistance	$V_{GS} = -10\text{ V}, I_D = -4\text{ A}^b$	-	0.625	0.75	Ω
I _{GSS}	Gate-Source Leakage	$V_{GS} = \pm 20\text{ V}$	-	-	± 100	nA
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -200\text{ V}, V_{GS} = 0\text{ V}$	-	-	-100	μA
		$V_{DS} = -160\text{ V}, V_{GS} = 0\text{ V}, T_J = 125^\circ\text{C}$	-	-	-500	
g _{fs}	Forward Transconductance	$V_{DS} = -50\text{ V}, I_D = -2.2\text{ A}$	1.1	-	-	S
C _{iss}	Input Capacitance	$V_{GS} = 0\text{ V},$ $V_{DS} = -25\text{ V}, f = 1.0\text{ MHz},$	-	590	770	pF
C _{oss}	Output Capacitance		-	140	180	
C _{rss}	Reverse Transfer Capacitance		-	25	35	
Q _g	Total Gate Charge	$I_D = -7.3\text{ A}, V_{DS} = -160\text{ V}, V_{GS} = -10\text{ V}$	-	-	20	nC
Q _{gs}	Gate-Source Charge		-	-	3.3	
Q _{gd}	Gate-Drain Charge		-	-	11	
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -100\text{ V}, I_D = -7.3\text{ A}, R_G = 18\ \Omega,$ $R_D = 25\ \Omega,$	-	8.8	-	ns
t _r	Rise Time		-	27	-	
t _{d(off)}	Turn-Off Delay Time		-	7.3	-	
t _f	Fall Time		-	19	-	
I _S	Continuous Source-Drain Diode Current	MOSFET symbol showing the integral reverse $p-n$ junction diode	-	-	-3.6	A
I _{SM}	Pulsed Diode Forward Current ^a		-	-	-14	
V _{SD}	Body Diode Voltage	$T_J = 25^\circ\text{C}, I_S = -5.7\text{ A}, V_{GS} = 0\text{ V}^b$	-	-	-6.3	V
t _{rr}	Body Diode Reverse Recovery Time	$T_J = 25^\circ\text{C}, I_F = -7.3\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}^b$	-	150	300	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	0.97	2.0	μC
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)				

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. L = 26.3mH, I_{AS} = -5.7A, V_{DD} = -50V, R_G = 25 Ω , Starting $T_J = 25^\circ\text{C}$
3. I_{SD} \leq -7.3A, di/dt \leq 300A/ μs , V_{DD} \leq BV_{DSS}, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width \leq 300 μs , Duty cycle \leq 2%
5. Essentially independent of operating temperature

200V P-Channel Enhancement Mode MOSFET

Typical Characteristics

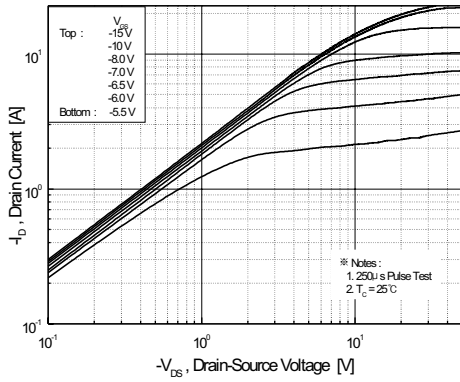


Figure 1. On-Region Characteristics

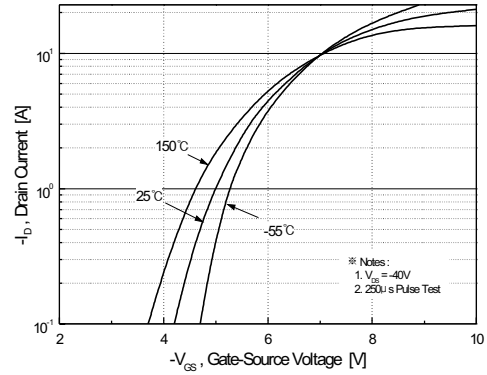


Figure 2. Transfer Characteristics

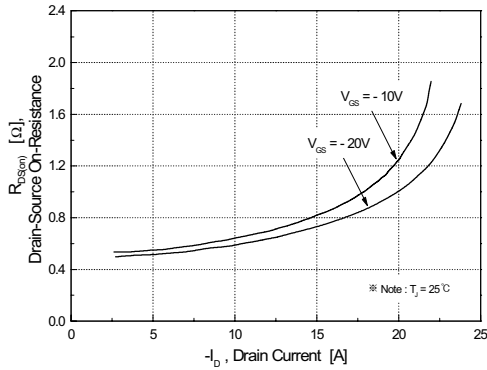


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

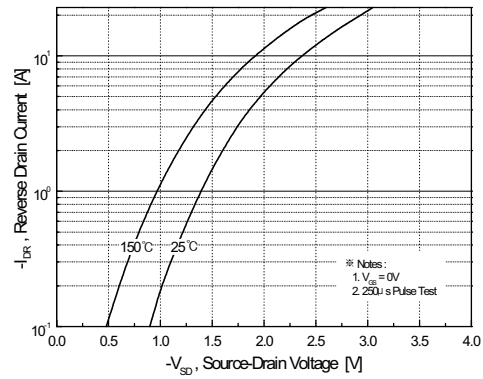


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

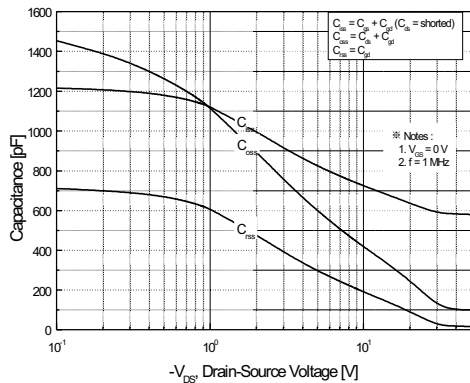


Figure 5. Capacitance Characteristics

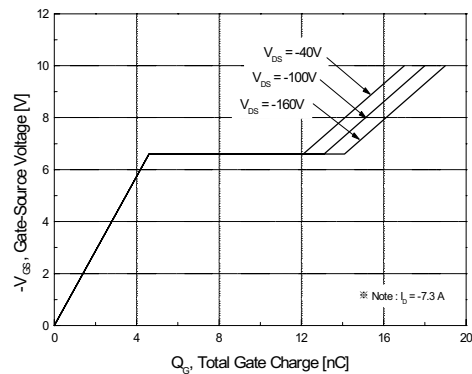


Figure 6. Gate Charge Characteristics

200V P-Channel Enhancement Mode MOSFET

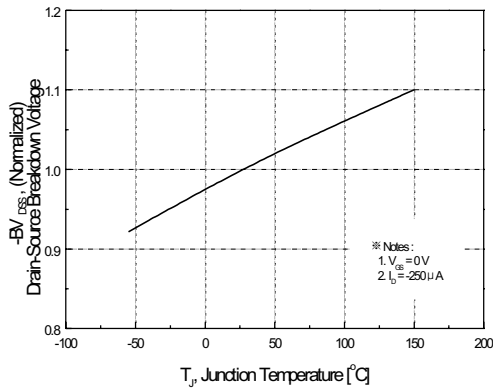


Figure 7. Breakdown Voltage Variation vs. Temperature

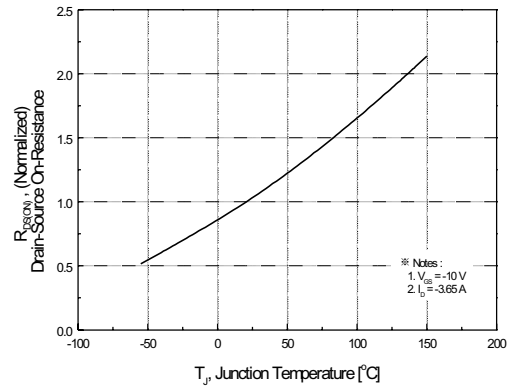


Figure 8. On-Resistance Variation vs. Temperature

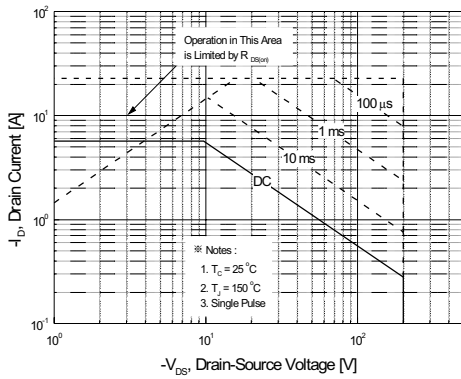


Figure 9. Maximum Safe Operating Area

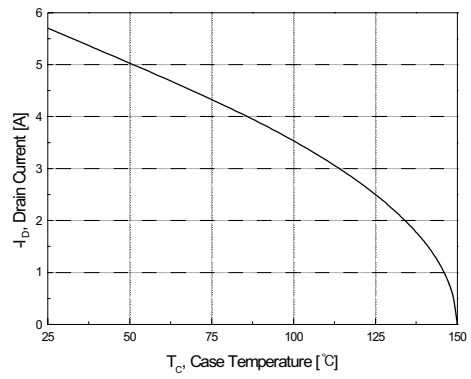


Figure 10. Maximum Drain Current vs. Case Temperature

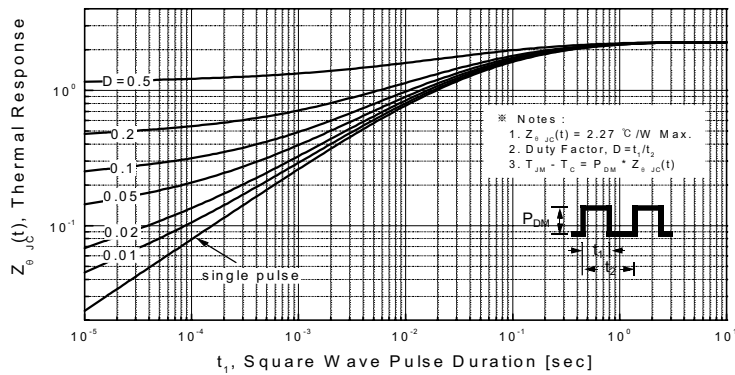
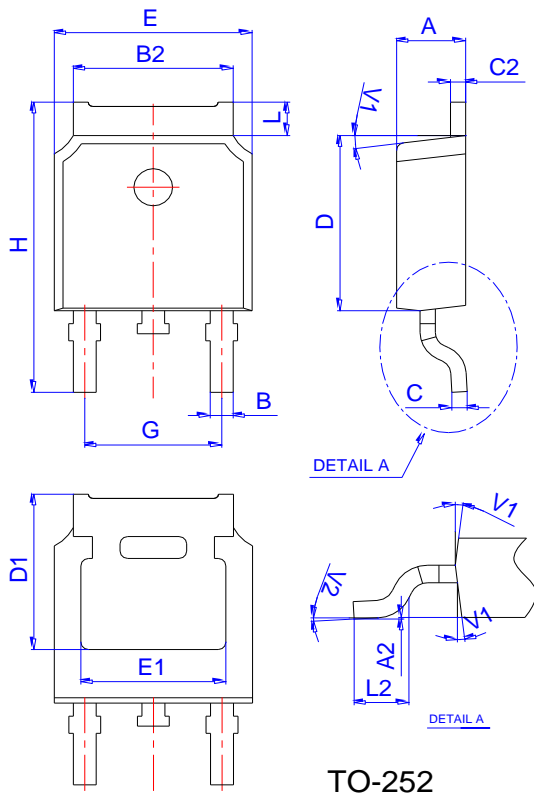


Figure 11. Transient Thermal Response Curve

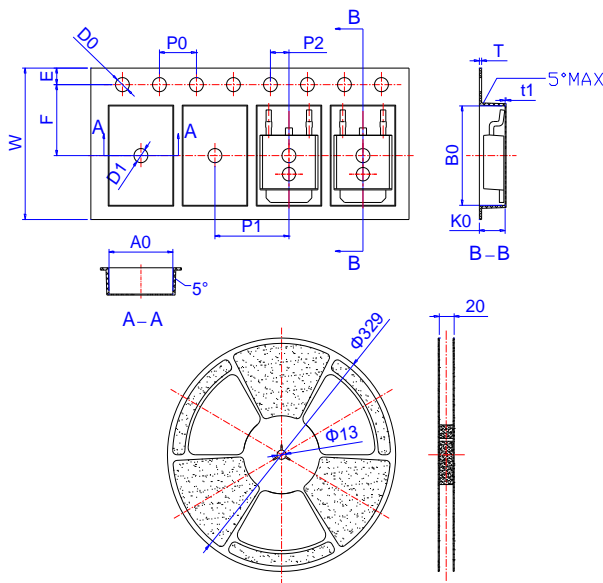
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Package Mechanical Data: TO-252-3L



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Specification-TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583